



Product Change Notification: CBOL-23BPQK156

Date:

28-Jul-2026

Product Category:

Capacitive Touch Sensors

Notification Subject:

CCB 7549.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for CAP1293-1-SN-TR, CAP1203-1-SN, CAP1293-1-SN, CAP1203-2-SN-TR and CAP1203-1-SN-TR catalog part numbers (CPN) available in 8L SOIC (3.90mm(.150in)) package.

Affected CPNs:

[CBOL-23BPQK156_Affected_CPN_07282026.pdf](#)

[CBOL-23BPQK156_Affected_CPN_07282026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for CAP1293-1-SN-TR, CAP1203-1-SN, CAP1293-1-SN, CAP1203-2-SN-TR and CAP1203-1-SN-TR catalog part numbers (CPN) available in 8L SOIC (3.90mm(.150in)) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes

Die Attach Material	8390A (PFAS-free)	8390A (PFAS-free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No
DAP Surface Prep	Ag Spot plated	Bare Cu	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 16 October 2026 (date code: 2642)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2026					>	October 2026				
Work Week	27	28	29	30	31		40	41	42	43	44
Qual Report Availability					X						
Final PCN Issue Date					X						
Estimated Implementation Date									X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB#7549.

Revision History: July 28, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN CBOL-23BPQK156_Qual Report_CCB7549.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

CAP1293-1-SN-TR

CAP1203-1-SN

CAP1293-1-SN

CAP1203-2-SN-TR

CAP1203-1-SN-TR



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: CBOL-23BPQK156

Date
April 24, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for CAP1293-1-SN-TR, CAP1203-1-SN, CAP1293-1-SN, CAP1203-2-SN-TR and CAP1203-1-SN-TR catalog part numbers (CPN) available in 8L SOIC (3.90mm(.150in)) package.



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Package Qualification Report

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for CAP1293-1-SN-TR, CAP1203-1-SN, CAP1293-1-SN, CAP1203-2-SN-TR and CAP1203-1-SN-TR catalog part numbers (CPN) available in 8L SOIC (3.90mm(.150in)) package.

CCB No: 7549

Misc.	Assembly site	MTAI
	Qual ID	R2501593 Rev. A
	BD Number	BD-003154/01
	MP Code (MPC)	TG105YD3XE1C
	Part Number (CPN)	CAP1298-1-SL-TR
	Assembly Shipping Media (T/R, Tube/Tray)	T/R
	Base Quantity Multiple (BQM)	2600
Lead-Frame	Paddle size	95 x 155
	Material	CDA194
	DAP Surface Prep	Bare Cu
	Treatment	Roughening
	Process	Stamped
	Lead-lock	No
	Part Number	10101411
Bond Wire	Lead Plating	Matte tin
	Material	CuPdAu
Die Attach	Part Number	8390A
	Conductive	Yes
MC	Part Number	G600V
PKG	PKG Type	SOIC
	Pin/Ball Count	14
	PKG width/size	150 mils



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Package Qualification Report

Manufacturing Information

Assembly Lot No.
MTAI263700612.000
MTAI263700698.000
MTAI263700700.000

Result

☒ Pass ☐ Fail ☐ _____

Qualification of TG105 mask / CAP1298-1-SL-TR product / CuPdAu wire in 14L SOIC 150 mils (D3X) package at MTAI site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards



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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2501593-1 MTAI263700612.000	R2501593-2 MTAI263700698.000	R2501593-3 MTAI263700700.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: FUSION_MX / EX_HCOVI	25°C		
Result	Passed		



MICROCHIP Package Qualification Report

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 504 hours		
Required Sample Size	45 units each lot / 3 lots;		
Lot ID	R2501593-1 MTAI263700612.000	R2501593-2 MTAI263700698.000	R2501593-3 MTAI263700700.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: FUSION_MX / EX_HCOVI	25°C		
Result	Passed		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-65°C / +150°C Air to Air / 500 Cycles		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2501593-1 MTAI263700612.000	R2501593-2 MTAI263700698.000	R2501593-3 MTAI263700700.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: FUSION_MX / EX_HCOVI	25°C		
Result	Passed		



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Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2501593-1 MTAI263700612.000	R2501593-2 MTAI263700698.000	R2501593-3 MTAI263700700.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: FUSION_MX / EX_HCOVI	25°C		
Result	Passed		

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2501593-1 MTAI263700612.000	R2501593-2 MTAI263700698.000	R2501593-3 MTAI263700700.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: FUSION_MX / EX_HCOVI	25°C		
Result	Passed		

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Visual Result (Fail / Pass)	0/5
Result	Passed

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Result	Passed